In the Claims:

- 1. (Currently amended) A dynamically controllable photonic crystal comprising:
- a) a structure having a periodic variation in dielectric constant, the structure including a substrate characterized by a substrate refractive index, said structure further including at least one <u>isolated resonant</u> local defect; and
- b) means to induce a local change in said substrate refractive index in the vicinity of said at least one local defect, thereby affecting dynamically the propagation of an electromagnetic wave through said structure.
- 2. (Original) The dynamically controllable photonic crystal of claim 1, wherein said substrate is a semiconductor substrate.
- 3. (Original) The dynamically controllable photonic crystal of claim 2, wherein said means to induce a local change in said substrate refractive index include means to induce local carrier refraction in the vicinity of said at least one local defect.
- 4. (Original) The dynamically controllable photonic crystal of claim 3, wherein said means to induce local carrier refraction include means to inject free charge carriers into said semiconductor substrate.
- 5. (Original) The dynamically controllable photonic crystal of claim 3, wherein said means to induce local carrier refraction include means to deplete charge carriers from said semiconductor substrate.
- 6. (Currently amended) The dynamically controllable photonic crystal of claim 4, wherein said semiconductor substrate includes a three-layer structure with two

junctions, said three-layer structure further characterized by having a center layer with a [higher] <u>lower</u> equilibrium carrier concentration than the concentrations of two external layers, and wherein said means to inject free charge carriers include electrical biases [applied separately to each said junction for injecting said carriers into said center layer].

- 7. (Currently amended) The dynamically controllable photonic crystal of claim [4] 5, wherein said semiconductor substrate includes a three-layer structure with two junctions, said three-layer structure further characterized by having a center layer with a [lower] higher equilibrium carrier concentration than the concentrations of two external layers, and wherein said means to deplete free charge carriers include electrical biases [applied separately to each said junction for depleting carriers from said center layer].
- 8. (Currently amended) The dynamically controllable photonic crystal of claim 6, wherein said three-layer structure with two junctions includes a structure selected from the group consisting of a PIN structure, a PNP structure, a [n] NPN structure, a [n] N⁺NN⁺ structure, a P⁺PP⁺ structure and a MSM structure.
- [8] 9. (Original) The dynamically controllable photonic crystal of claim 7, wherein said three-layer structure with two junctions includes a structure selected from the group consisting of a PN⁺P structure, a NP⁺N structure, a NN⁺N structure, and a PP⁺P structure.
- [9] 10. (Original) The dynamically controllable photonic crystal of claim 2, wherein said semiconductor is silicon.
- [10] 11. (Currently amended) A dynamically controllable silicon photonic crystal comprising:

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a) a silicon substrate with a periodic array of air rods disposed therewithin, said silicon substrate further including at least one isolated resonant local defect; and

b) means to induce electrically a local carrier refraction change in the vicinity of said at least one <u>isolated resonant</u> local defect, thereby affecting dynamically an electromagnetic wave propagating through the photonic crystal.

[11] 12. (Currently amended) The dynamically controllable silicon photonic crystal of claim [10] 11, wherein said air rods are circular, with a diameter larger than that of said at least one local defect.

[12] 13. (Currently amended) The dynamically controllable silicon photonic crystal of claim [10] 11, wherein said means to induce electrically a local carrier refraction include means to inject charge carriers locally into said silicon substrate.

[13] 14. (Currently amended) The dynamically controllable silicon photonic crystal of claim [10] 11, wherein said means to induce electrically a local carrier refraction change include means to deplete charge carriers locally from said silicon substrate.

[14] 15. (Currently amended) The dynamically controllable silicon photonic crystal of claim [12] 13, wherein said silicon substrate includes a three-layer structure with two junctions, said three-layer structure further characterized by having a center layer with a [higher] lower equilibrium carrier concentration than the concentrations of two external layers, and wherein said means to inject free charge carriers include electrical biases [applied separately to each said junction for injecting said carriers into said center layer].

[15] 16. (Currently amended) The dynamically controllable silicon photonic crystal of claim [13] 14, wherein said silicon substrate includes a three-layer structure with two junctions, said three-layer structure further characterized by having a center layer

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with a [lower] higher equilibrium carrier concentration than the concentrations of two external layers, and wherein said means to deplete free charge carriers include electrical biases [applied separately to each said junction for depleting carriers from said center layer].

[16] 17. (Currently amended) The dynamically controllable silicon photonic crystal of claim [14] 15, wherein said three-layer structure with two junctions includes a structure selected from the group consisting of a PIN structure, a PNP structure, a[n] NPN structure, a[n] N⁺NN⁺ structure, a P⁺PP⁺ structure and a MSM structure.

[17] 18. (Currently amended)) The dynamically controllable silicon photonic crystal of claim [15] 16, wherein said three-layer structure with two junctions includes a structure selected from the group consisting of a PN⁺P structure, a NP⁺N structure, a NN⁺N structure, and a PP⁺P structure.

[18] 19. (Original) A dynamically controllable photonic bandgap device comprising:

- a photonic crystal with at least one micro-cavity formed in a substrate, said at least one micro-cavity configured to dynamically manipulate an optical beam; and
 - b) electrical means to facilitate said manipulation.
- [19] 20. (Currently amended) The device of claim [18] 19, wherein said substrate is a semiconductor substrate, and wherein said electrical means include means to induce electrically local carrier refraction in the vicinity of said at least one micro-cavity.
- [20] 21. (Currently amended) The device of claim [19] 20, wherein means to induce said local carrier refraction include means to inject charge carriers locally into said semiconductor substrate in the vicinity of said at least one micro-cavity.

- [21] 22. (Currently amended) The device of claim [19] 20, wherein means to induce said local carrier refraction include means to deplete charge carriers locally from said semiconductor substrate in the vicinity of said at least one micro-cavity.
- [22]23. (Currently amended) The device of claim [18]19, wherein said semiconductor substrate is silicon.
- [23] 24 (Currently amended) The device of claim [22] 20, selected from the group consisting of a tunable optical filter, a tunable optical router, a tunable optical modulator and an optical switch.
- [24] 25 (Original) A method for dynamically controlling electromagnetic wave motion through a photonic crystal comprising the steps of:
- a) providing a photonic crystal having a substrate characterized by a substrate index of refraction, said photonic crystal further having at least one microcavity, the electromagnetic wave motion interacting with said at least one microcavity; and
- b) electrically affecting a parameter of said at least one micro-cavity, thereby affecting the electromagnetic wave motion through the photonic crystal.
- [25] 26. (Currently amended) The method of claim [24] 25, wherein said affected parameter is a resonance frequency of said at least one micro-cavity, and wherein said step of electrically affecting said resonance frequency includes electrically inducing a local index change in said substrate index of refraction, in the vicinity of said at least one micro-cavity.
- [26] 27. (Currently amended) The method of claim [25] 26, wherein said substrate is

silicon, and wherein said substep of electrically inducing a local index change includes locally changing a carrier concentration in said silicon substrate, in the vicinity of said at least one micro-cavity, thereby causing a local carrier refraction effect.

[27] 28. (Currently amended) The method of claim [26] 27, wherein said substep of locally changing a carrier concentration includes increasing said carrier concentration by injecting excess carriers.

[28] 29. (Currently amended) The method of claim [26] 27, wherein said substep of locally changing a carrier concentration includes decreasing said carrier concentration by extracting carriers selected from the group of excess carriers and equilibrium carriers.

- [29] 30. (Currently amended) The method of claim [26] 27, wherein said substep of locally changing a carrier concentration is performed using a device selected from the group consisting of two terminal devices and three-terminal devices.
- [30] 31. (Currently amended) The method of claim [29] 30, wherein said two and three terminal devices include devices selected from the group consisting from unipolar devices, bipolar devices, metal semiconductor devices and metal-oxide-semiconductor devices.
- [31] 32. (Original) A method for dynamically controlling a photonic bandgap device built on a substrate, comprising the steps of:
- a) forming in said substrate at least one micro-cavity that resonates at a given frequency; and

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- b) inducing a slight dielectric constant alteration of the substrate in the vicinity of said at least one micro-cavity to obtain a fine resonance tuning of said frequency, thereby obtaining a finely tuned control of an electromagnetic wave propagating in the device.
- [32] 33. (Currently amended) The method of claim [31] 32, wherein said step of inducing includes inducing said slight dielectric constant alteration of the substrate electrically.
- [33] 34. (Currently amended) The method of claim [32] 33, wherein the substrate is a semiconductor substrate, and wherein said step of electrically inducing said slight dielectric constant alteration includes electrically inducing carrier refraction.
- [34] 35. (Currently amended) The method of claim [33] 34, wherein said step of electrically inducing carrier refraction includes an electric field induced action selected from the group consisting of carrier injection and carrier depletion.